

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13702	
1.3 Title of PCN	AMKOR ATP (Philippines) TSSOP20 package HDLF to XDLF conversion for STM8AF6213x and STM8AF6223x listed AUTOMOTIVE products	
1.4 Product Category	TSSOP 20 package products listed- automotive products - STM8AF6213x - STM8AF6223x	
1.5 Issue date	2022-11-03	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	Amkor ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	PCBR HDLF to XDLF Conversion AMKOR TSSOP20 Auto (79J) Current line in Amkor: - Leadframe: Pre-Plated Frame (PPF) , High Density Leadframe (HDLF) - Second level interconnect : e4	Converted line: - Leadframe : Tin Post-plated Frame, Extreme Density Leadframe (XDLF) - Second level interconnect : e3
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Lead color and surface finish will change due to different leadframe finishing.	

5. Reason / motivation for change

5.1 Motivation	Pushed by HDLF line obsolescence we will convert to C194 material
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2022-10-17
7.2 Intended start of delivery	2023-04-17
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13702 MDG-GPM-RER2218 PCN13702 ATP1 TSSOP20.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-11-03
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9. Attachments (additional documentations)
13702 Public product.pdf 13702 MDG-GPM-RER2218 PCN13702 ATP1 TSSOP20.pdf 13702 PCN13702_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM8AF6223PAU	

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